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(54) Title: NO-FLOW FLUX ADHESIVE COMPOSITIONS

(57) Abstract: The invention provides adhesives and adhesive compositions that comprise epoxy resin and non-volatile anhydride. One embodiment further comprises a hydroxyl containing compound that is insoluble in the epoxy resin/anhydride blend at mixing temperatures which reacts with the anhydride at solder reflow temperatures to form a fluxing agent in-situ. Another embodiment further comprises catalyst.

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